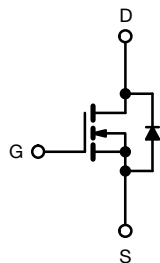
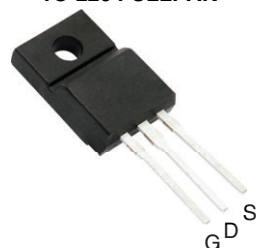


# Power MOSFET

**TO-220 FULLPAK**


N-Channel MOSFET

## FEATURES

- Isolated package
- High voltage isolation = 2.5 kV<sub>RMS</sub> (t = 60 s; f = 60 Hz)
- Sink to lead creepage distance = 4.8 mm
- 175 °C operating temperature
- Dynamic dV/dt rating
- Low thermal resistance
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

## DESCRIPTION

Third generation power MOSFETs from Vishay provides the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

## PRODUCT SUMMARY

V <sub>DS</sub> (V)	100	
R <sub>DS(on)</sub> (Ω)	V <sub>GS</sub> = 10 V	0.54
Q <sub>g</sub> max. (nC)	8.3	
Q <sub>gs</sub> (nC)	2.3	
Q <sub>gd</sub> (nC)	3.8	
Configuration	Single	

## ORDERING INFORMATION

Package	TO-220 FULLPAK
Lead (Pb)-free	IRFI510GPbF

## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V <sub>DS</sub>	100	V
Gate-source voltage			V <sub>GS</sub>	± 20	
Continuous drain current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	I <sub>D</sub>	4.5	A
		T <sub>C</sub> = 100 °C		3.2	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	18	
Linear derating factor				0.18	W/°C
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	60	mJ
Repetitive avalanche current <sup>a</sup>			I <sub>AR</sub>	4.5	A
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	2.7	mJ
Maximum power dissipation	T <sub>C</sub> = 25 °C		P <sub>D</sub>	27	W
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	4.5	V/ns
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300	
Mounting torque	M3 screw			0.6	

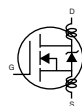

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- V<sub>DS</sub> = 25 V, starting T<sub>J</sub> = 25 °C, L = 4.4 mH, R<sub>g</sub> = 25 Ω, I<sub>AS</sub> = 4.5 A (see fig. 12)
- I<sub>SD</sub> ≤ 5.6 A, dI/dt ≤ 75 A/ms, V<sub>DD</sub> ≤ V<sub>DS</sub>, T<sub>J</sub> ≤ 175 °C
- 1.6 mm from case

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	65	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	5.5	

**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

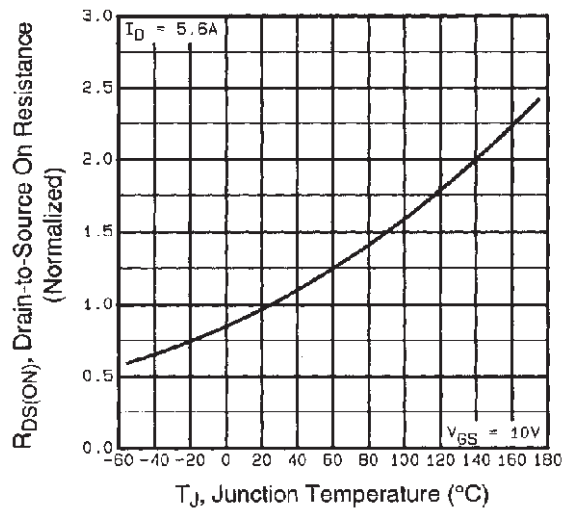
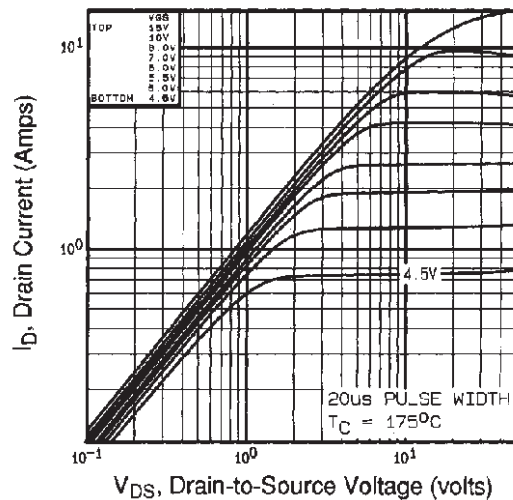
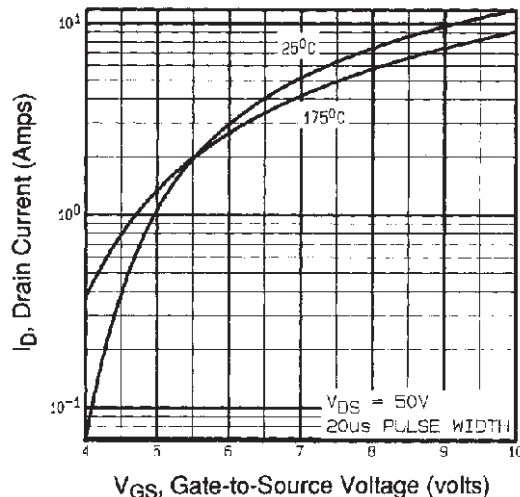
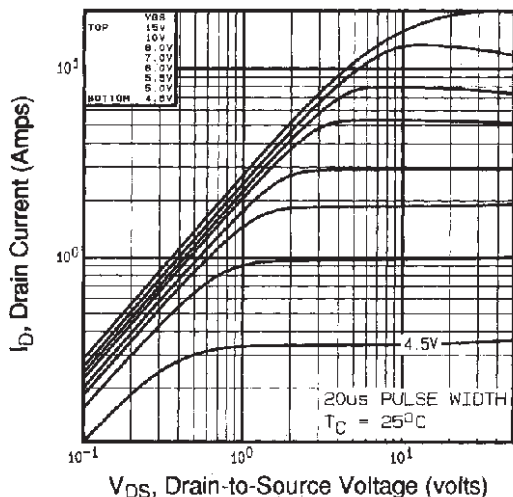
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-ssource breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$		100	-	-	V
$V_{DS}$ temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D = 1\text{ mA}$		-	0.63	-	V/ $^{\circ}\text{C}$
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-source leakage	$I_{GSS}$	$V_{GS} = \pm 20$		-	-	$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 100\text{ V}$ , $V_{GS} = 0\text{ V}$		-	-	25	$\mu\text{A}$
		$V_{DS} = 80\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 150\text{ }^{\circ}\text{C}$		-	-	250	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 2.7\text{ A}^b$	-	-	0.54	$\Omega$
Forward transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}$ , $I_D = 2.7\text{ A}^b$		1.2	-	-	S
Dynamic							
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ $V_{DS} = 25\text{ V}$ $f = 1.0\text{ MHz}$ , see fig. 5		-	180	-	pF
Output capacitance	$C_{oss}$			-	81	-	
Reverse transfer capacitance	$C_{rss}$			-	15	-	
Drain to sink capacitance	$C$	$f = 1.0\text{ MHz}$		-	12	-	
Total gate charge	$Q_g$	$V_{GS} = 10\text{ V}$	$I_D = 5.6\text{ A}$ , $V_{DS} = 80\text{ V}$ , see fig. 6 and 13 <sup>b</sup>	-	-	8.3	nC
Gate-source charge	$Q_{gs}$			-	-	2.3	
Gate-drain charge	$Q_{gd}$			-	-	3.8	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 50\text{ V}$ , $I_D = 5.6\text{ A}$ $R_g = 24\text{ }\Omega$ , $R_D = 8.4\text{ }\Omega$ , see fig. 10 <sup>b</sup>		-	6.9	-	ns
Rise time	$t_r$			-	16	-	
Turn-off delay time	$t_{d(off)}$			-	15	-	
Fall time	$t_f$			-	9.4	-	
Gate input resistance	$R_g$	$f = 1\text{ MHz}$ , open drain		0.8	-	4.2	$\Omega$
Internal drain inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	nH
Internal source inductance	$L_S$			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	4.5	A
Pulsed diode forward current <sup>a</sup>	$I_{SM}$			-	-	18	
Body diode voltage	$V_{SD}$	$T_J = 25\text{ }^{\circ}\text{C}$ , $I_S = 4.5\text{ A}$ , $V_{GS} = 0\text{ V}^b$		-	-	2.5	V
Body diode reverse recovery time	$t_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = 5.6\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}^b$		-	100	200	ns
Body diode reverse recovery charge	$Q_{rr}$			-	0.44	0.88	$\mu\text{C}$
Forward turn-on time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

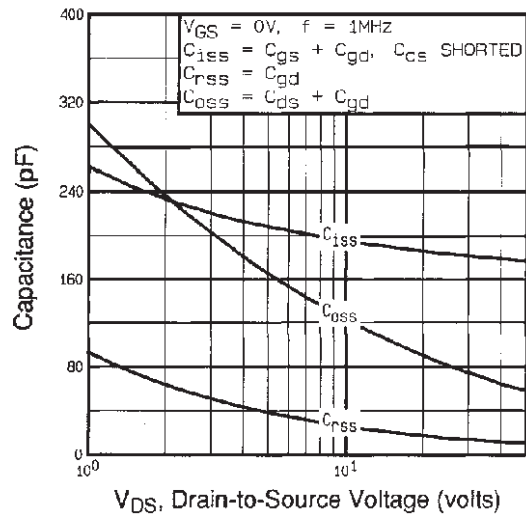
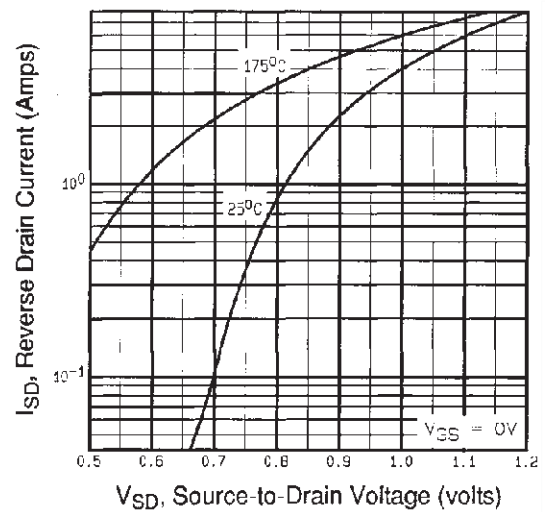
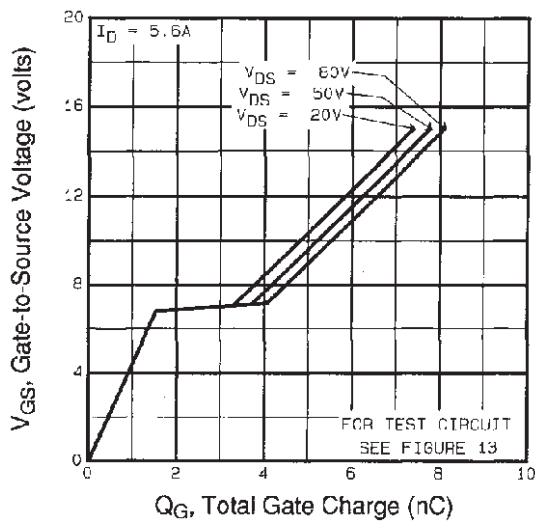
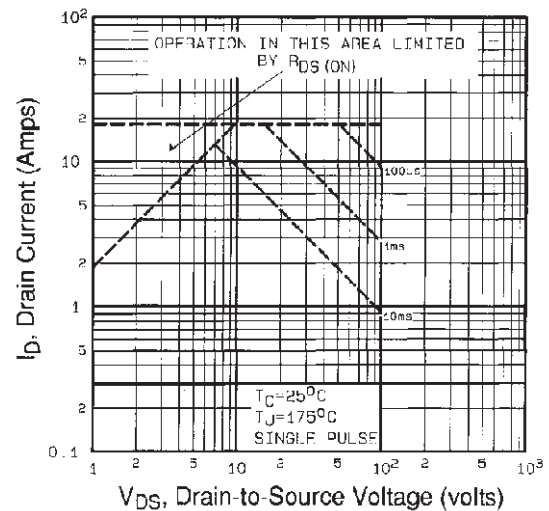
**Notes**

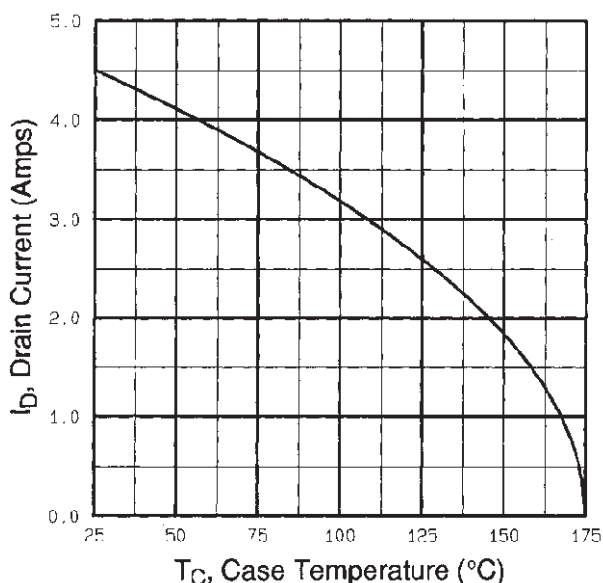
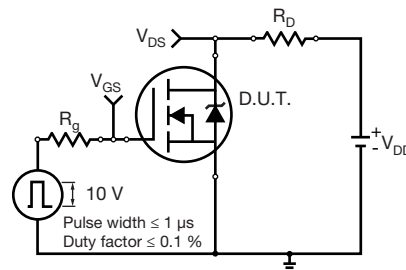
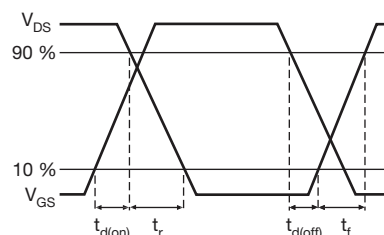
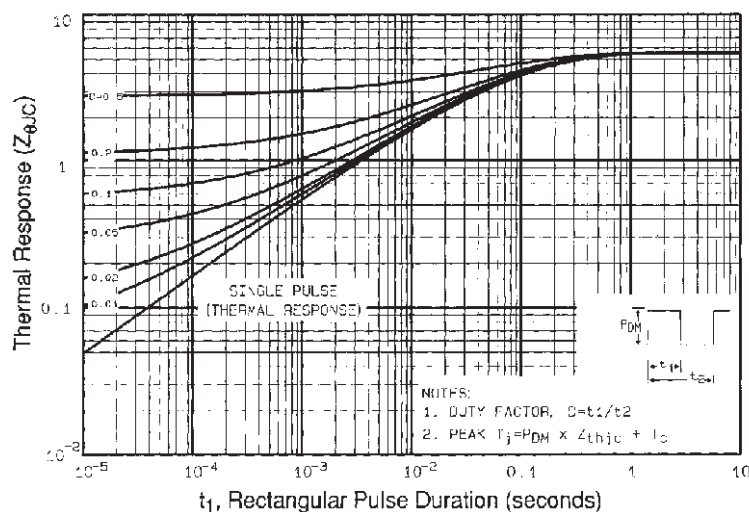
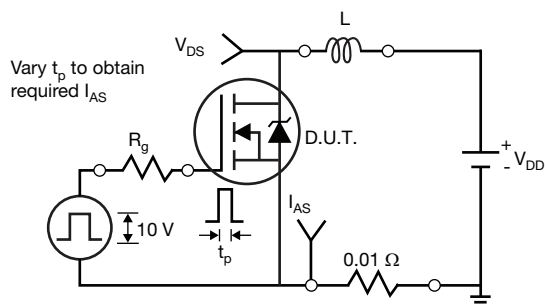
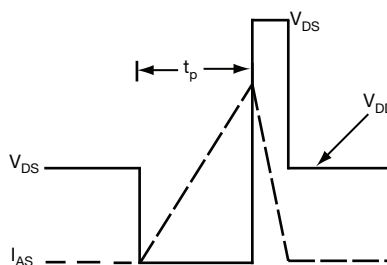
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)  
b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$

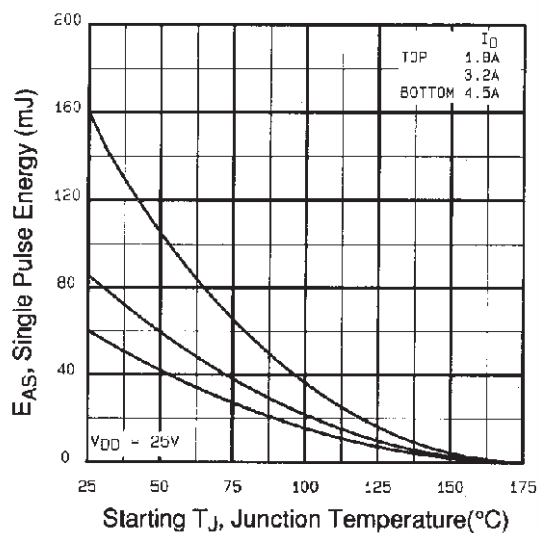


**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

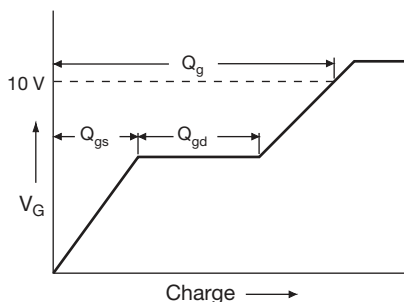



**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 7 - Typical Source-Drain Diode Forward Voltage**

**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**

**Fig. 8 - Maximum Safe Operating Area**

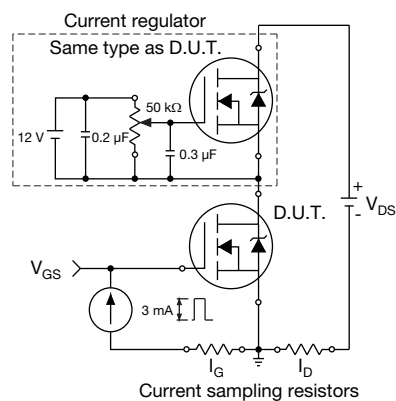

**Fig. 9 - Maximum Drain Current vs. Case Temperature**

**Fig. 10a - Switching Time Test Circuit**

**Fig. 10b - Switching Time Waveforms**

**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**Fig. 12a - Unclamped Inductive Test Circuit**

**Fig. 12b - Unclamped Inductive Waveforms**



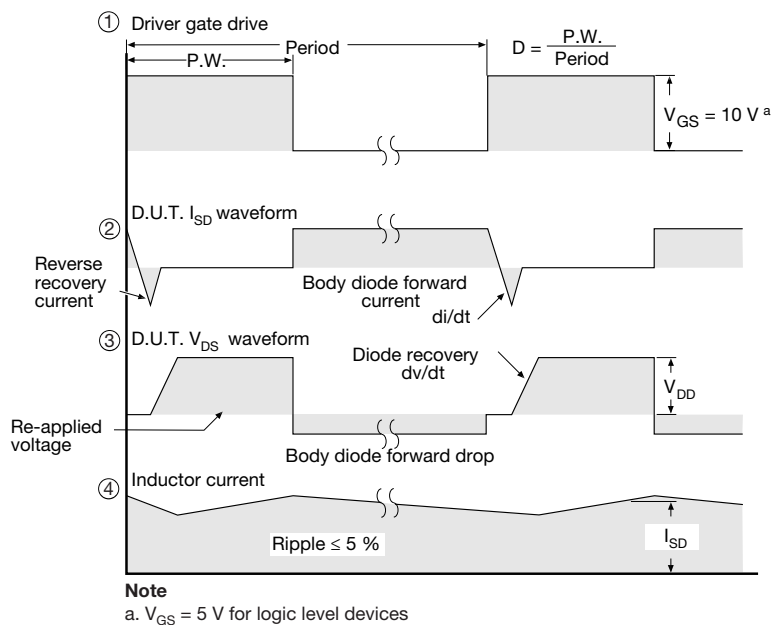
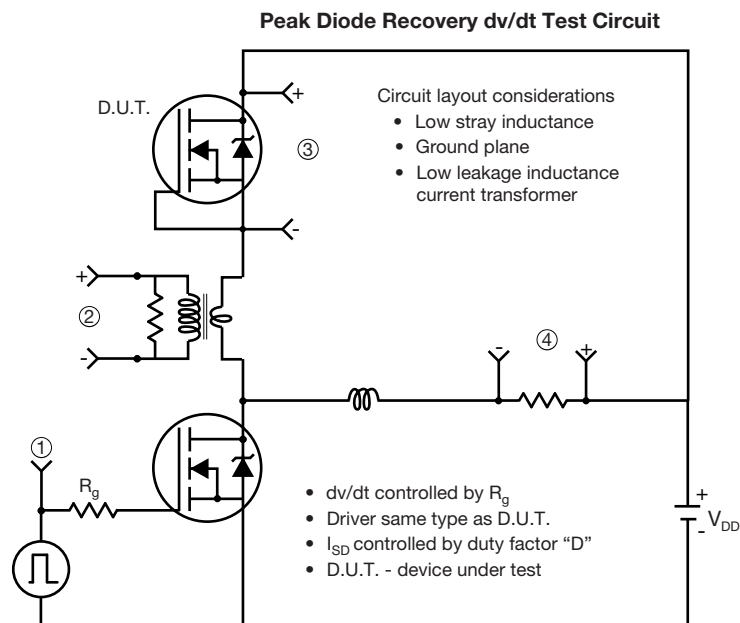
**Fig. 12c - Maximum Avalanche Energy vs. Drain Current**



**Fig. 13a - Basic Gate Charge Waveform**



**Fig. 13b - Gate Charge Test Circuit**

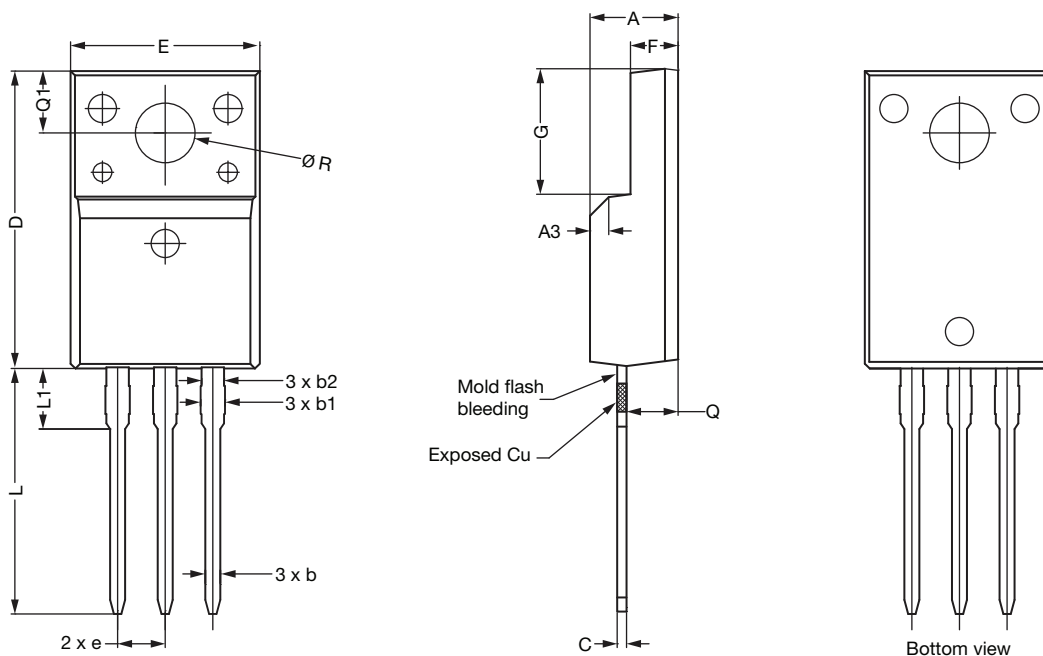


**Fig. 14 - For N-Channel**

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## TO-220 FULLPAK (High Voltage)

### OPTION 1: FACILITY CODE = 9



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
C	0.45	0.50	0.63
D	15.80	15.87	15.97
e	2.54 BSC		
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
Ø R	3.08	3.18	3.28

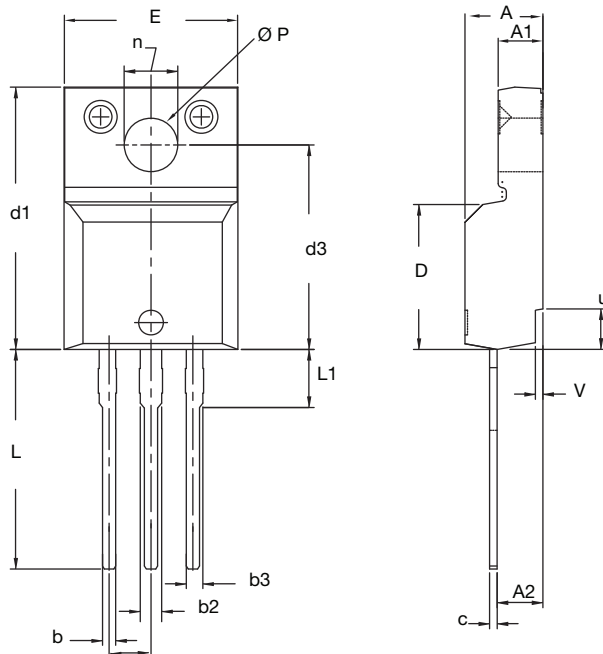
#### Notes

1. To be used only for process drawing
2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet  $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
5. No chipping or package damage
6. Facility code will be the 1<sup>st</sup> character located at the 2<sup>nd</sup> row of the unit marking





## OPTION 2: FACILITY CODE = Y



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
c	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
e	2.54 BSC		0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
Ø P	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

ECN: E19-0180-Rev. D, 08-Apr-2019  
DWG: 5972

## Notes

1. To be used only for process drawing
2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet  $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
5. No chipping or package damage
6. Facility code will be the 1<sup>st</sup> character located at the 2<sup>nd</sup> row of the unit marking



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